

Title (en)
METHOD FOR PRODUCING A HERMETICALLY SEALED, ELECTRICAL FEEDTHROUGH USING EXOTHERMIC NANOFILM

Title (de)
VERFAHREN ZUR ERZEUGUNG EINER HERMETISCH DICHTEN, ELEKTRISCHEN DURCHFÜHRUNG MITTELS EXOTHERMER NANOFOLIE

Title (fr)
PROCÉDÉ DE PRODUCTION D'UNE TRAVERSÉE ÉLECTRIQUE HERMÉTIQUEMENT ÉTANCHE À L'AIDE D'UN NANOFILM EXOTHERME

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Application
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Abstract (en)
[origin: WO2009133105A1] The present invention relates to a method for generating at least one electrical connection (1) from at least one electronic component (7), which is positioned on a substrate (3) inside an encapsulation (5), to outside the encapsulation (5). The functional capability of the electrical connection (1) is to be provided at ambient temperatures greater than 140 °C and in the event of large power losses and extreme environmental influences. The invention is characterized in that a reactive nanofilm (2), having targeted reaction, which can be triggered exothermically by laser, is used to produce hermetically sealed electrical connections (1). Using the nanofilm (2), an output of an electrical connection (1) and a contact of the electrical connection (1) to at least one further electrical contact can be provided.

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